

Title (en)

PALLADIUM AND PALLADIUM ALLOYS ELECTROPLATING PROCEDURE.

Title (de)

ELEKTROPLATTIERUNGSVERFAHREN FÜR PALLADIUM UND PALLADIUMLEGIERUNGEN.

Title (fr)

PROCEDE DE REVETEMENT PAR ELECTRODEPOSITION DE PALLADIUM ET DES ALLIAGES DE PALLADIUM.

Publication

**EP 0073236 A1 19830309 (EN)**

Application

**EP 82901061 A 19820218**

Priority

US 23915181 A 19810227

Abstract (en)

[origin: EP0059452A2] A procedure for electroplating palladium and palladium alloys is disclosed which permits rapid and efficient plating and yields ductile, adherent palladium films. The electroplating bath comprises a unique complex of palladium and aliphatic polyamine the latter having from 3 to 20 carbon atoms and may have at least one substituent selected from hydrogen, hydroxide, chloride and bromide. The bath is highly stable and does not adversely affect the base material being plated.

Abstract (fr)

Procede de revetement par electrodeposition d'alliages de palladium permettant un placage rapide et efficace et produisant des pellicules de palladium ductiles et adherentes. Le bain de revetement (13) comprend un complexe unique de palladium et d'une polyamine aliphatique, cette derniere possedant de 3 a 20 atomes de carbone et pouvant avoir au moins un substituant selectionne entre l'hydrogene, un hydroxyde, un chlorure et un bromure. Le bain est tres stable et n'agit pas negativement sur le materiau de base (11) soumis au placage.

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